RB520S30

200 mA low VF MEGA Schottky barrier rectifier

7 April 2021 **Product data sheet**

1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD523 (SC-79) ultra small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 0.2$ A
- Reverse voltage: $V_R \leq 30$ V
- Low reverse current: $I_R \leq 1$ uA
- AEC-Q101 qualified
- Ultra small and flat lead SMD plastic package

3. Applications

- Low current rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Low power consumption applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	δ = 0.5; f = 20 kHz; square wave; $T_{amb} \leq$ 105 °C	[1]	-	-	200	mA
		δ = 0.5; f = 20 kHz; square wave; $T_{sp} \leq$ 135 °C		-	-	200	mA
I_R	reverse current	V_R = 10 V; T_j = 25 °C		-	-	1	µA
V_R	reverse voltage	T_j = 25 °C		-	-	30	V
V_F	forward voltage	I_F = 200 mA; $t_p \leq$ 300 µs; δ ≤ 0.02; pulsed; T_j = 25 °C		-	520	600	mV

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.

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5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 SC-79 (SOD523)	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
RB520S30	SC-79	plastic, surface-mounted package; 2 leads; 1.2 mm x 0.8 mm x 0.6 mm body	SOD523

7. Marking

Table 4. Marking codes

Type number	Marking code
RB520S30	ZA

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	T_j = 25 °C		-	30	V
$I_{F(AV)}$	average forward current	δ = 0.5; f = 20 kHz; square wave; T_{amb} ≤ 105 °C	[1]	-	200	mA
		δ = 0.5; f = 20 kHz; square wave; T_{sp} ≤ 135 °C		-	200	mA
I_{FSM}	non-repetitive peak forward current	t_p = 8.3 ms; half sine wave; $T_{j(init)}$ = 25 °C		-	1	A
P_{tot}	total power dissipation	T_{amb} ≤ 25 °C	[2]	-	275	mW
			[1]	-	420	mW
			[3]	-	500	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

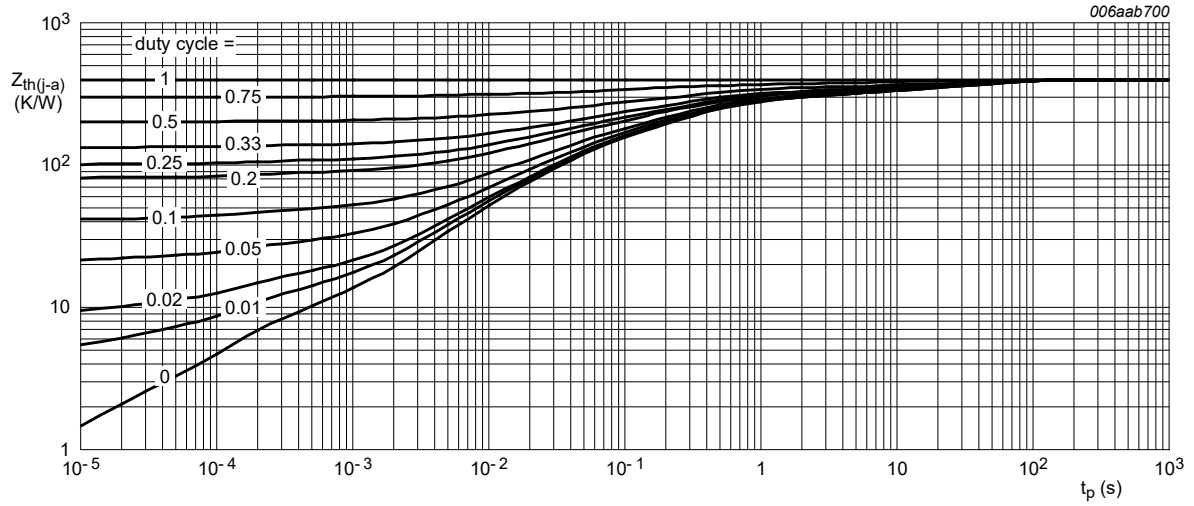
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[3] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.

9. Thermal characteristics

Table 6. Thermal characteristics

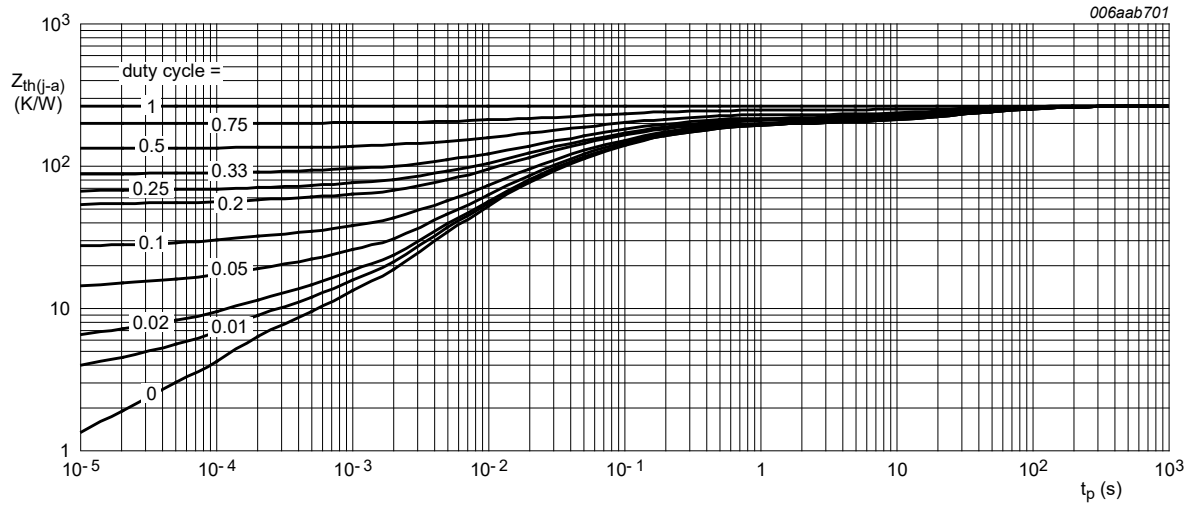
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	455	K/W
			[1] [3]	-	-	300	K/W
			[1] [4]	-	-	250	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[1] [5]	-	-	90	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.
[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.
[4] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.
[5] Soldering point of cathode tab.



FR4 PCB, standard footprint

Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



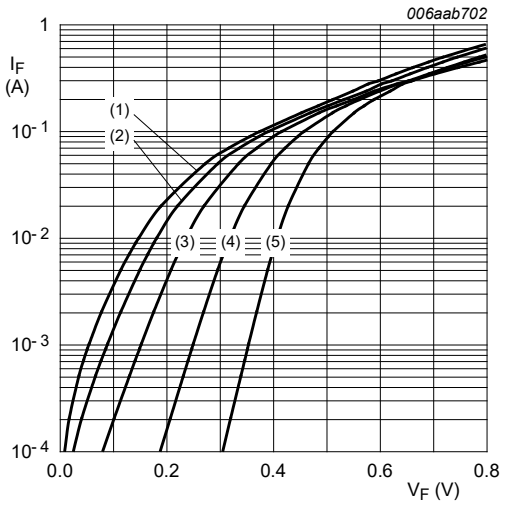
FR4 PCB, mounting pad for cathode 1 cm^2

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

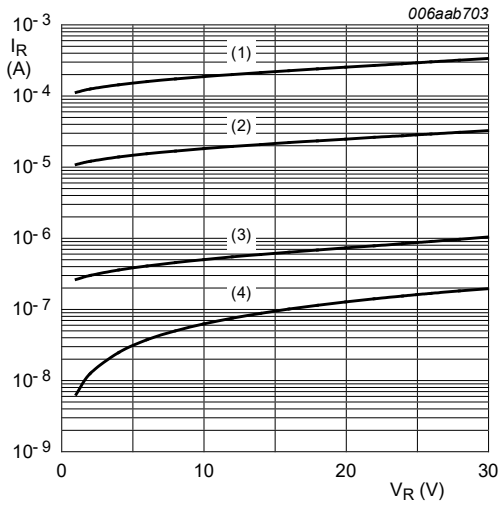
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_F	forward voltage	I_F = 0.1 mA; $t_p \leq$ 300 µs; $\delta \leq$ 0.02; pulsed; T_j = 25 °C		-	190	220	mV
		I_F = 1 mA; $t_p \leq$ 300 µs; $\delta \leq$ 0.02; pulsed; T_j = 25 °C		-	250	290	mV
		I_F = 10 mA; $t_p \leq$ 300 µs; $\delta \leq$ 0.02; pulsed; T_j = 25 °C		-	320	360	mV
		I_F = 100 mA; $t_p \leq$ 300 µs; $\delta \leq$ 0.02; pulsed; T_{amb} = 25 °C		-	440	500	mV
		I_F = 200 mA; $t_p \leq$ 300 µs; $\delta \leq$ 0.02; pulsed; T_j = 25 °C		-	520	600	mV
I_R	reverse current	V_R = 10 V; T_j = 25 °C		-	-	1	µA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz; T_j = 25 °C		-	-	20	pF



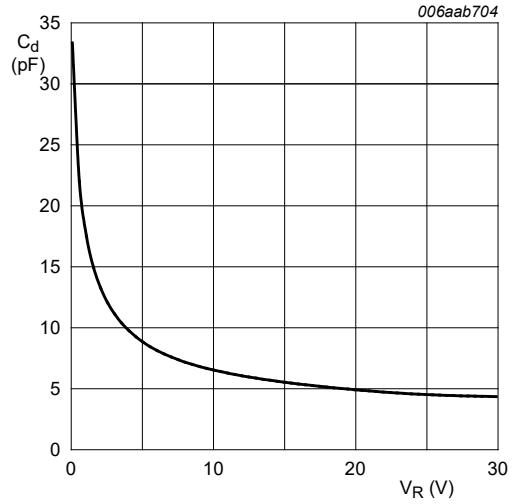
(1) T_j = 150 °C
(2) T_j = 125 °C
(3) T_j = 85 °C
(4) T_j = 25 °C
(5) T_j = -40 °C

Fig. 3. Forward current as a function of forward voltage; typical values



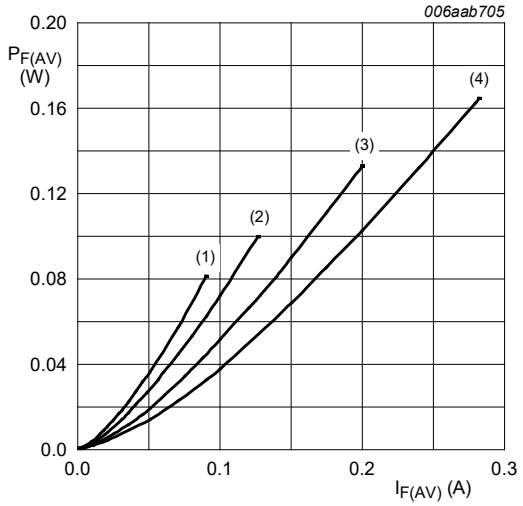
(1) T_j = 125 °C
(2) T_j = 85 °C
(3) T_j = 25 °C
(4) T_j = -40 °C

Fig. 4. Reverse current as a function of reverse voltage; typical values



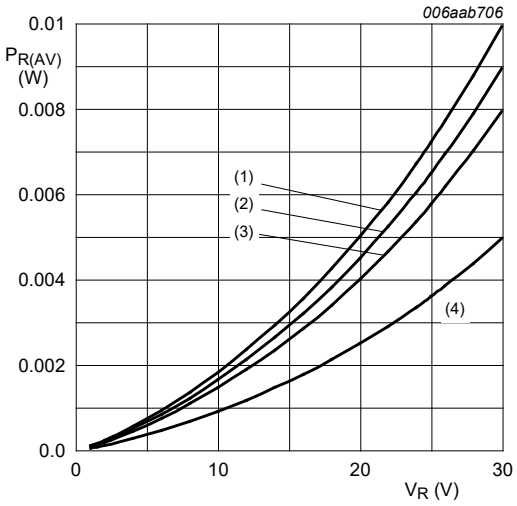
f = 1 MHz; T_{amb} = 25 °C

Fig. 5. Diode capacitance as a function of reverse voltage; typical values



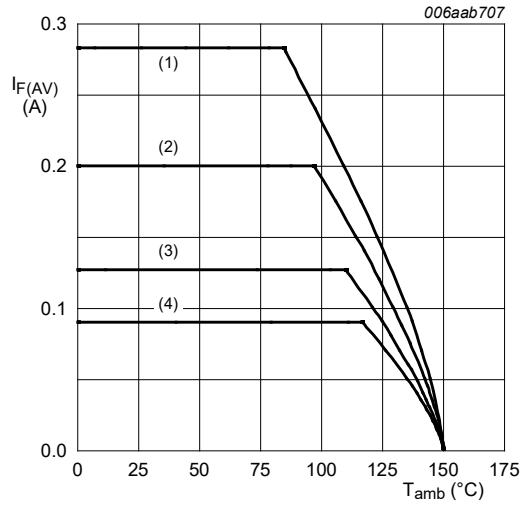
T_j = 150 °C
(1) δ = 0.1
(2) δ = 0.2
(3) δ = 0.5
(4) δ = 1

Fig. 6. Average forward power dissipation as a function of average forward current; typical values



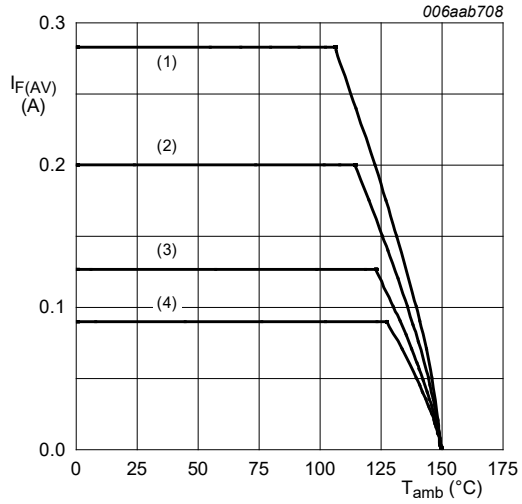
T_j = 125 °C
(1) δ = 1
(2) δ = 0.9
(3) δ = 0.8
(4) δ = 0.5

Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values



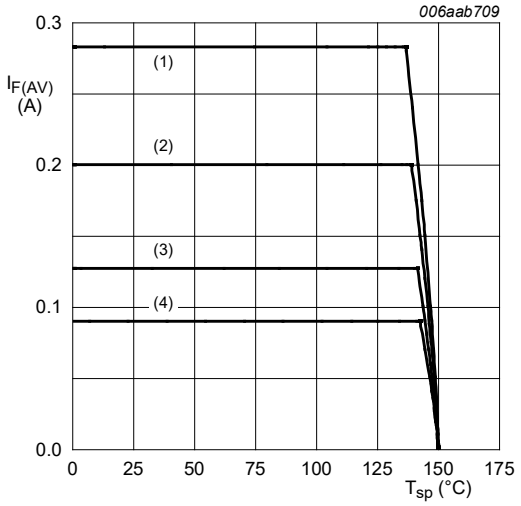
FR4 PCB, standard footprint
T_j = 150 °C
(1) δ = 1; DC
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 8. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm^2
T_j = 150 °C
(1) δ = 1; DC
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

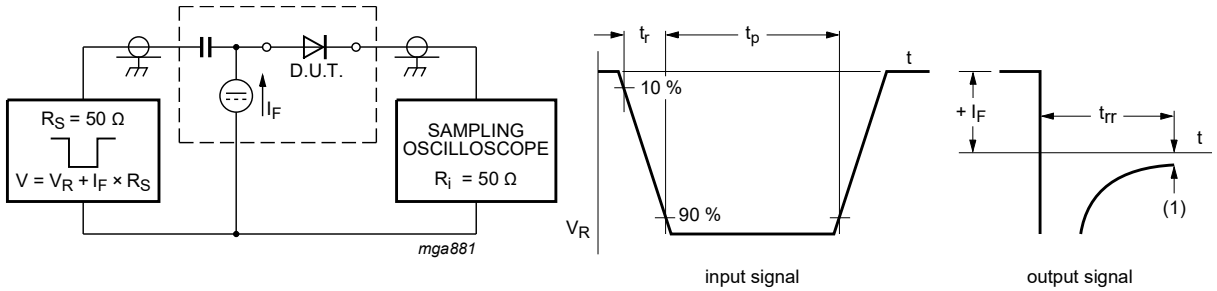
Fig. 9. Average forward current as a function of ambient temperature; typical values



T_j = 150 °C
(1) δ = 1; DC
(2) δ = 0.5; f = 20 kHz
(3) δ = 0.2; f = 20 kHz
(4) δ = 0.1; f = 20 kHz

Fig. 10. Average forward current as a function of solder point temperature; typical values

11. Test information



(1) I_R = 1 mA
Input signal: reverse pulse rise time t_r = 0.6 ns; reverse voltage pulse duration t_p = 100 ns; duty cycle δ = 0.05
Oscilloscope rise time t_r = 0.35 ns

Fig. 11. Reverse recovery time: test circuit and waveforms

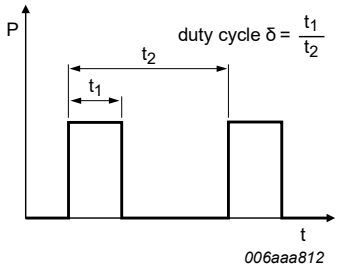


Fig. 12. Duty cycle definition

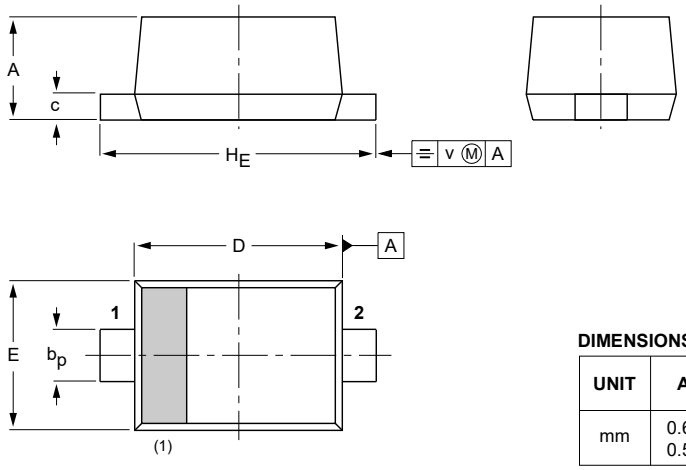
The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

Plastic surface-mounted package; 2 leads **SOD523**



DIMENSIONS (mm are the original dimensions)

UNIT	A	b_p	c	D	E	H_E	v
mm	0.65 0.58	0.34 0.26	0.17 0.11	1.25 1.15	0.85 0.75	1.65 1.55	0.1

Note

1. The marking bar indicates the cathode.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOD523			SC-79			~~02-12-13~~ 06-03-16

Fig. 13. Package outline SC-79 (SOD523)

13. Soldering

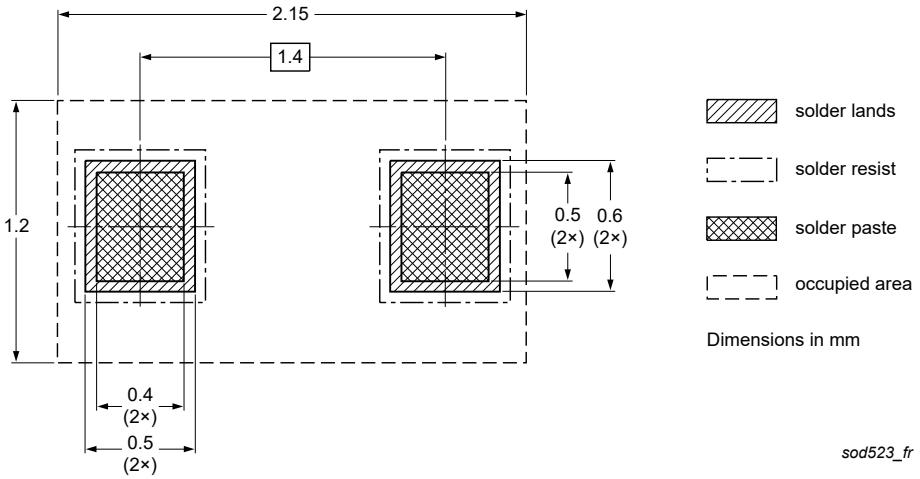


Fig. 14. Reflow soldering footprint for SC-79 (SOD523)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
RB520S30 v.2	20210407	Product data sheet	-	RB520S30 v.1
Modifications:	• Soldering: reflow soldering footprint drawing changed. • The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. • Legal texts have been adapted to the new company name where appropriate.			
RB520S30 v.1	20091006	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 7 April 2021